AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior versions, and all prior listings, of claims in the application:

Listing of the Claims:

Claims 1 and 2 (Cancelled).

- 3. (Currently Amended) The A photosensitive resin composition according to claim 2_11, wherein said diamine is a diaminopolysiloxane.
- 4. (Currently Amended) The A photosensitive resin composition according to claim 111, wherein said transmittance is in a range of 40%-68%.

Claims 5-9 (Cancelled).

10. (Currently Amended) A photosensitive resin composition which comprises (1) a polyimide precursor formed from produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and (b) at least one diamine selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, metaphenylene diamine, p-phenylenediamine, p-xylylenediamine, diaminonaphthalene, dimethylbenzidine, dimethoxylbenzidine, diaminodiphenylmethane, diaminodiphenylsulfide, benzophenonediamine, bis{(aminophenoxy) phenyl}sulfone, hexafluorobis(aminophenyl)propane, bis{(aminophenoxy)phenyl}propane, dimethyl-

diaminophenyl-methane, tetramethyl-diaminodiphenylmethane, bis{(aminophenoxy)phenyl} sulfone, bis(aminophenyl)propane and diaminopolysiloxanewith a diamine, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an iline stepper which uses monochromatic light, the polyimide precursor being such that a 20 μ m thick film thereof has a transmittance, at 365nm, of at least 40%.

- 11. (Original) A photosensitive resin composition according to claim 10, wherein the addition-polymerizable compound is tetraethylene glycol dimethacrylate.
- 12. (Original) A photosensitive resin composition according to claim 11, wherein said diamine is a diaminodiphenyl ether.
- 13. (Original) A photosensitive resin composition according to claim 10, wherein said diamine is a diaminodiphenyl ether.

Claims 14-16 (Cancelled).

17. (Currently Amended) A photosensitive resin according to claim—14_13, wherein the diamine is selected from the group consisting of 4,4'-diaminodiphenyl ether, 2,4'-diaminodiphenyl ether, 3,4'-diaminodiphenyl ether and 3,3'-diaminodiphenyl ether.

Claim 18 (Cancelled)

- 19. (New) A photosensitive resin composition according to claim 10, wherein said at least one diamine is selected from the group consisting of 4, 4'-diaminodiphenyl ether, 2, 4'-diaminodiphenyl ether, 3, 4'-diaminodyphenyl ether 3, 3'-diaminodiphenyl ether, 4, 4'-diaminodiphenyl sulfone, 3, 3'-diaminodiphenyl sulfone and metaphenylenediamine.
- 20. (New) A photosensitive resin composition according to claim 19, wherein said at least one diamine is selected from the group consisting of 3, 4'-diaminodiphenyl ether, 3, 3'-diaminodiphenyl sulfone, 4, 4'-diaminodiphenyl sulfone and methaphenylenediamine.
- 21. (New) A photosensitive resin composition according to claim 10, wherein the at least one diamine includes a diaminopolysiloxane represented by the formula (III):

(III):
$$H_{2}N - R^{5} \left(\begin{array}{c} R^{7} \\ Si - O \\ R^{8} \end{array} \right) \begin{array}{c} R^{7} \\ Si - R^{6} - NH_{2} \end{array}$$
(III)

wherein R⁵ and R⁶ each represent a divalent hydrocarbon group; R⁷ and R⁸ each represent a monovalent hydrocarbon group; each of R⁵, R⁶, R⁷ and R⁸ may be the same or different; and t represents an integer of 1 to 5.

- 22. (New) A photosensitive resin composition according to claim 21, wherein said divalent hydrocarbon group has 1 to 3 carbon atoms, and said monovalent hydrocarbon group has 1 to 3 carbon atoms.
- 23. (New) A photosensitive resin composition which comprises (1) a polyimide precursor produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and (b) at least one diamine including a hydroxyl group-containing diamine, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20 μ m thick film thereof has a transmittance, at 365 nm, of at least 40%.